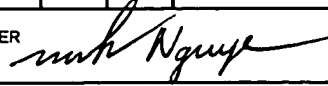


Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			ATTY. DOCKET NO. M122-1684		SERIAL NO. 09/827,248		
<div style="display: flex; align-items: center; justify-content: center;"> <div style="border: 2px solid black; border-radius: 50%; padding: 10px; text-align: center; margin-right: 20px;"> OIP LIST OF ARTS CITED BY APPLICANT (Use several sheets if necessary) JAN 28 2002 PATENT & TRADEMARK OFFICE </div> <div style="font-size: 2em; margin-left: 20px;">6</div> </div>					APPLICANT David Hembree			FILING DATE April 4, 2001	
					GROUP 2838				
U.S. PATENT DOCUMENTS									
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate			
<div style="font-size: 2em;">✓</div> <div style="font-size: 2em;">↓</div> <div style="font-size: 2em;">✓</div>	AA	5,612,574	3/18/97	Summerfelt et al.					
	AB	5,719,333	2/17/98	Hosoi et al.					
	AC	5,831,333	11/3/98	Malladi et al.					
	AD	5,919,548	7/6/99	Barron et al.					
	AE	5,551,283	9/3/96	Manaka et al.					
	AF	5,492,011	2/20/96	Amano et al.					
	AG								
	AH								
	AJ								
FOREIGN PATENT DOCUMENTS									
	Document Number	Date	Country	Class	Subclass	Translation			
						Yes	No		
	AK								
	AL								
	AM								
	AN								
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)									
	AD	"NTC and PTC Thermistors"; http://www.thermoseco.com/ntpte.html ; 1/2/98; 3 pages.							
	AR	"DI 5B35 Linearized 4 Wire RTD Input"; http://www.dataq.com/di5b35.html ; 1/2/98; 3 pages.							
	AS	"RTD"; http://www.mticensors.com/rtd.html ; 1/2/98; 3 pages.							
	AT	"Low Cost Thermal Ribbon (TM) uses thin film RTD"; http://www.minco.com/el1624mr.html ; 1/2/98; 1 page.							
	AU	"Silicon Processing for the VLSI Era"; Volume 1 - Process Technology, Second Edition; S. Wolf et al.; 2000; pps 22-25 and pps 641-645.							
EXAMINER				DATE CONSIDERED					
				10/18/2002					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1684	SERIAL NO. 09/827,248	
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				APPLICANT David R. Hemberge FILING DATE April 4, 2001		GROUP 2829
U.S. PATENT DOCUMENTS						
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
VN	AA 3,440,407	4/22/69	Golstos et al.			
	AB 3,614,345	10/19/71	Quinn			
	AC 3,683,306	8/8/72	Buthius et al.			
	AD 4,332,081	6/1/82	Francis			
	AE 4,518,944	5/21/85	Faris			
	AF 4,703,555	11/3/87	Hubner			
	AG 5,141,334	8/25/92	Castles			
	AH 5,347,869	9/20/94	Shie et al.			
	AI 5,406,109	4/11/95	Whitney			
	AJ 5,430,646	7/25/95	McArthur et al.			
	AK 5,446,437	8/29/95	Bantien et al.			
FOREIGN PATENT DOCUMENTS						
	Document Number	Date	Country	Class	Subclass	Translation
						Yes No
	AL 2336778	7/10/77	France			
	AM 56-12521	2/1981	Kobayashi, Japan			
	AN 2-268462	11/1990	Yamanishi, Japan			
	AO					
	AP					
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)						
	AR	Application Guide Temperature Sensors, Watlow Electrical Manufacturing Company, Catalog, pp. 713-778, 1992/1993.				
	AS	In Situ Survey System of Resistance and Thermoelectric Properties of Either Pure or Mixed Materials in Thin Films Exposed to Ultra High Vacuum, Leckemiller, Lohmann, Ruckes, Savon, & Gensh, J. Phys. III, France, Vol. 3, pp. 409-418, 04/96 (Abstract only).				
	AT	Temperature Metrology for CD Control in DUV Lithography, Jeffrey Daxner and Wayne Becken, pp. 111-113, 114, 116, 00/1/2002.				
EXAMINER			DATE CONSIDERED			
			10/18/2002			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.						

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE JUL 29 2002 PATENT & TRADEMARK OFFICE		ATTY. DOCKET NO. M122-16804	PRIORITY SERIAL NO. 09/137,629		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT David R. Hembree			
				PRIORITY FILING DATE August 21, 1998	PRIORITY GROUP 2858		
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	4,360,216	12/24/85	Egawa			
	AB	4,754,555	7/5/88	Sellman			
	AC	5,475,317	12/12/95	Smith			
	AD	5,495,667	3/5/96	Farnworth et al.			
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AE	SN: 09/032,164; Filed 2/27/98; Akram et al.; Amendment filed 12/13/00; CPA filed 7/28/00; Amendment filed 3/3/00; Amendment filed 8/23/00; Original Application filed 2/27/98; Pending Claims					
	AF	Advertisement for Probe Technology: www.idinet.com ; Interconnect Devices, Inc.; 1 page; 3/6/98					
	AG	Good Things Come in Small BGACSP Packages; www.johnstech.com/4/handbook/page0.html ; 1 page; 3/5/98					
	AH	Product Description for Double Ended Probes, B1052 Series; www.testprobe.com/products/b1052.html ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AI	Product Description for Test Centers, RM-500 Series Probes; www.testprobe.com/products/rm500.html ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AJ	Product Description for Cost Effective Interconnections for High I/O Products; www.testprobe.com/products/so.htm#b1303 ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AK	Product Description for Ball Grid Probe B1302-C3; www.testprobe.com/products/so.htm#b1303 ; Rika Denshi America, Inc.; 1 page; 2/4/98					
	AL	Product Description for Test Socket Contacts; www.johnstech.com/4/handbook/page0.html ; 1 page; 3/5/98					
EXAMINER <i>rubh Nguyen</i>				DATE CONSIDERED 03/10/03			
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

Form PTO-1449		<div style="position: relative; height: 40px;"> 9 <div style="position: absolute; top: 0; left: 0; width: 100%; height: 100%; border: 1px solid black; border-radius: 50%; text-align: center; line-height: 100px;"> U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE JUL 29 2002 RECEIVED & TRADEMARK OFFICE </div> </div>		ATTY. DOCKET NO. M122-1684	SERIAL NO. 09 327,248
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT David R. Hembree	
FILING DATE April 4, 2001			GROUP 3252 2829		

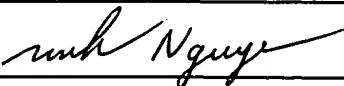
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA 3,440,407	4/22/69	Gotsis et al.			
	AB 3,614,345	10/19/71	Quen			
	AC 3,683,306	8/8/72	Bukhins et al.			
	AD 4,332,081	6/1/82	Francis			
	AE 4,518,944	5/21/85	Faris			
	AF 4,703,555	11/3/87	Hubner			
	AG 5,141,334	8/25/92	Castles			
	AH 5,347,869	9/20/94	Shie et al.			
	AI 5,406,100	4/11/95	Whitney			
	AJ 5,436,646	7/25/95	McArthur et al.			
	AK 5,446,437	8/29/95	Bunies et al.			

FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
VN	AL	2336778	7/1977	France				
VN	AM	56-12521	2/1981	Kobayashi, Japan				
VN	AN	2-268462	11/1990	Yamazaki, Japan				
	AO							
	AP							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)			
VN	AR		Application On-Chip Temperature Sensors, Watlow Electrical Manufacturing Company Catalog, pp. 775-778, 1992/1993. (month unavailable)
VN	AS		In-Situ Survey System of Resistive and Thermoelectric Properties of Either Pure or Mixed Materials in Thin Films Evaporated Under Ultra High Vacuum, Lechevallier, LeHouou, Richon, Sarras, & Gounth, J. Phys. III France, Vol. 3, pp. 409-418, 04/95 (Abstract only).
VN	AT		Temperature Metrology for CO Control in SOV Lining, Jeffery Parker and Wayne Reeken, pp. 111-112, 114, 116, 09/17/97.

EXAMINER <i>anh Nguyen</i>	DATE CONSIDERED 03/10/03
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Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. M122-1684		SERIAL NO. 09/827,248	
LIST OF ART CITED BY APPLICANT (Use separate sheets if necessary)				APPLICANT David Hembree		FILING DATE April 4, 2001	
U.S. PATENT DOCUMENTS				GROUP 2829			
Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA 5,612,574	3/18/97	Gummerfelt et al.				
	AB 5,719,333	2/17/98	Wosoi et al.				
	AC 5,831,333	11/3/98	Mahdavi et al.				
	AD 5,810,548	7/6/99	Barron et al.				
	AE 5,551,283	9/3/96	Manaka et al.				
	AF 5,492,011	2/20/96	Amano et al.				
	AG						
	AH						
	AJ						
FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
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	AL						
	AM						
	AN						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
VN	AP	"NTC and PTC Thermistors"; http://www.thermodisc.com/nicptc.html ; 1/7/98; 2 pages.					
VN	AR	"DI-5B35 Linearized 4-Wire RTD Input"; http://www.dataq.com/di5b35.html ; 1/7/98; 2 pages.					
VN	AS	"RTD"; http://www.mtisensors.com/rtos.html ; 1/7/98; 3 pages.					
VN	AT	"Low Cost Thermal-Ribbon (TM) uses thin film RTD"; http://www.minco.com/s17624nr.html ; 1/7/98; 1 page.					
VN	AU	"Silicon Processing for the VLSI Era"; Volume I - Process Technology, Second Edition; S. Wolf et al.; 2000; pps 22-25 and pps. 841-845.					
EXAMINER			DATE CONSIDERED				
			03/10/03				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							